

## Term 7- Sept 2025

# Nanoelectronics and Technology (01.119/99.503)-Week 2 Class 2

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25-Sept- 2025

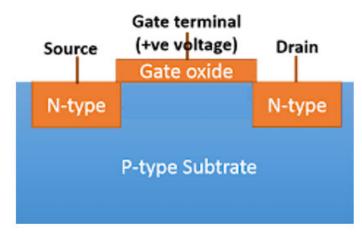
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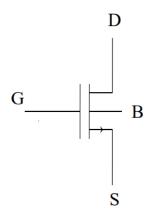
#### Outline

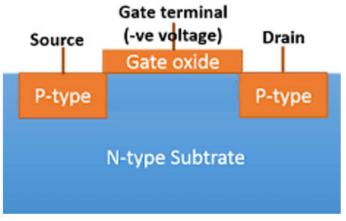
- MOSFET structure
- CMOS Inverter
- CMOS Based Digital Circuits
- Noise Margin



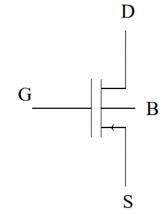


n-channel MOS Transistor





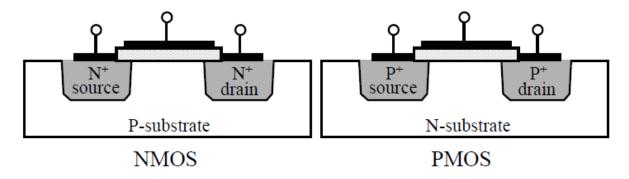
p-channel MOS Transistor



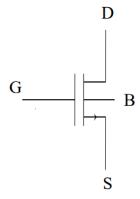


#### **MOS Transistor**

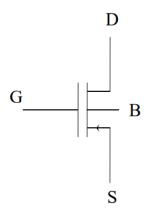
- Add "source" and "drain" terminals to MOS capacitor
- > Transistor types
  - ➤ NMOS: p-type substrate, n+ source/drain
  - ➤ PMOS: n-type substrate, p+ source/drain



#### n-channel MOS Transistor

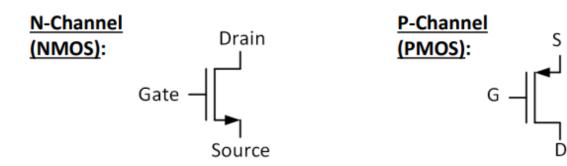


p-channel MOS Transistor

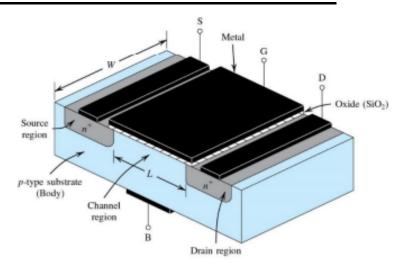


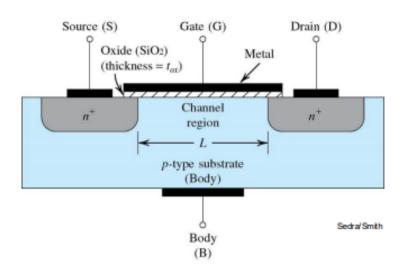


- We now turn our attention to another type of transistor, the MOSFET:
  - Metal Oxide Semiconductor Field Effect Transistor
- Many similarities to the BJT:
  - Three terminals
  - Voltage at one terminal controls current between the other two
    - A transconductance device
  - Two polarities: N-channel and P-channel MOSFETS
    - Our focus will primarily be N-channel MOSFETs (NMOS devices)









- P-type substrate
- N+ source and drain
- Metal gate electrode, and source/drain/body contacts
- Thin oxide insulates the gate from the rest of the device
- Region of substrate between the drain and source is the channel
  - Channel dimensions: W and L



- Terminal voltages and currents named as shown
  - Again, lower-case v/i and upper-case subscript represents total (AC and DC) voltage and current
- For an NMOS device in typical operation:

$$v_{GS} \geq 0$$

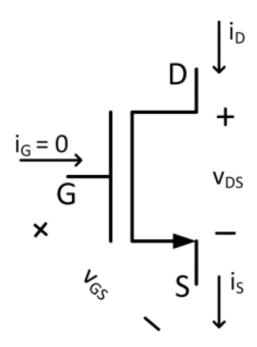
$$v_{DS} \geq 0$$

 Gate oxide does not allow current to flow, so

$$i_G = 0$$

and

$$i_D = i_S$$





#### **Cut-Off Region**

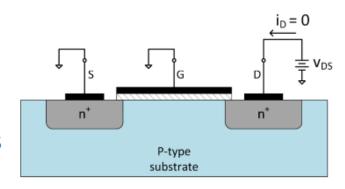
 Gate and source both grounded

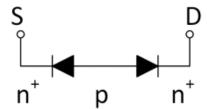
$$v_{GS}=0$$

- Drain-to-source pathway looks like two back-to-back diodes
  - Very high drain-source resistance ( $r_{DS} = \infty$ )
- $\hfill \Box$  Even for  $v_{DS}>0$  , no current will flow

$$i_D = 0$$

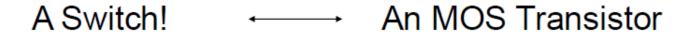
Looks like an open switch

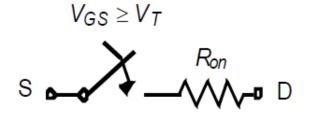


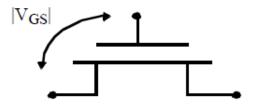




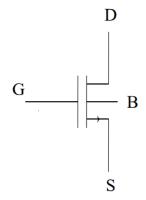
#### What is a Transistor?



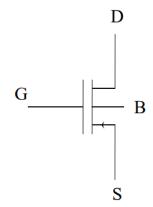




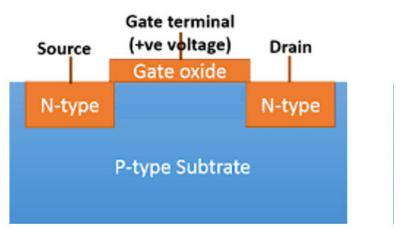




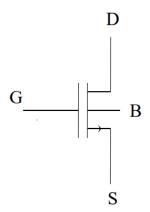
p-channel MOS Transistor







n-channel MOS Transistor





Inversion

S

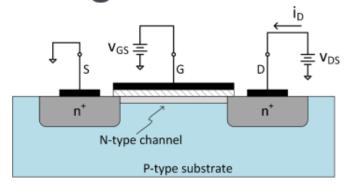
N-type channel

P-type substrate

- - Electric field established across gate oxide
  - Holes in p-type substrate repelled deeper into substrate
  - Electrons from drain and source attracted to region below the gate
- $\Box$  For large enough  $v_{GS}$ , p-type material below the gate is **inverted** to n-type
  - An inversion layer
  - Induced n-type channel connects drain to source
  - Now, current can flow in response to  $v_{DS}$ ,  $i_D>0$



#### Threshold Voltage



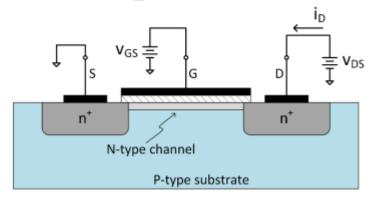
- $\Box$  Channel is induced once  $v_{GS}$  exceeds a certain voltage:
  - The threshold voltage

$$v_{GS} \ge V_t$$

- A device parameter
- Typically,  $V_t = 300 \text{ mV} \dots 1 \text{ V}$
- $\Box$  As  $v_{GS}$  increases beyond  $V_t$ , the induced channel gets deeper
- $\square$  As long as  $v_{DS}$  is small ( $v_{DS} \ll V_t$ ), channel depth is uniform



## Overdrive Voltage



- oxdot A channel is induced once  $v_{GS}$  exceeds the threshold voltage
- $v_{GS}$  in excess of the threshold voltage is called the **overdrive voltage** or **effective voltage**:

$$v_{OV} = v_{GS} - V_t$$

 $\ \square$  As we will soon see,  $v_{\mathit{OV}}$  plays an important role in determining device behavior



#### Channel formation basics

A channel forms when

$$V_{GS} > V_T$$

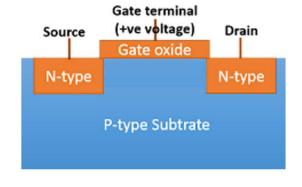
because inversion charge appears under the gate.

· Along the channel, the local inversion charge is

$$Q_n(x) \propto V_{GS} - V_T - V(x),$$

where V(x) is the channel potential at position x.

- At the source end,  $V(0)=0 \implies Q_n(0) \propto V_{GS} V_T$  (strong channel).
- At the drain end,  $V(L) = V_{DS} \implies Q_n(L) \propto V_{GS} V_T V_{DS}$ .





#### Condition for pinch-off

• At the source end,  $V(0)=0 \implies Q_n(0) \propto V_{GS} - V_T$  (strong channel).

• At the drain end,  $V(L) = V_{DS} \implies Q_n(L) \propto V_{GS} - V_T - V_{DS}$ .

• If  $V_{DS} < V_{GS} - V_T$ :

Channel charge is positive all along the channel → continuous inversion path from source to drain. MOSFET is in **linear/triode region**.

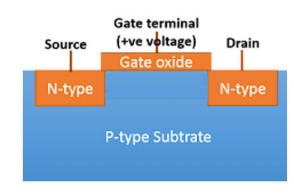
• If  $V_{DS} = V_{GS} - V_T$ : At the drain end,

$$Q_n(L) = 0$$

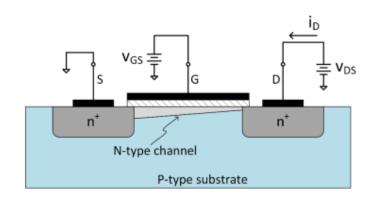
- → the inversion channel just disappears at the drain edge → onset of pinch-off.
- If  $V_{DS} > V_{GS} V_T$ :

No inversion possible near the drain. Instead:

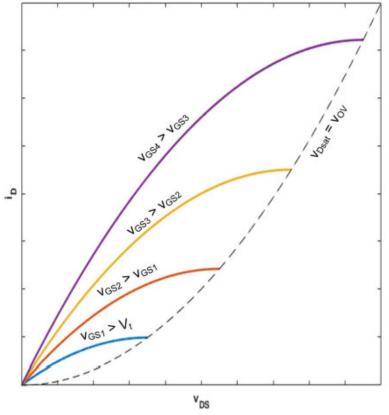
- Channel terminates at a "pinch-off point" before the drain.
- Beyond this, a depletion region carries the extra potential drop.
- Current saturates since the effective voltage across the channel is clamped at  $V_{GS}-V_{T}.$





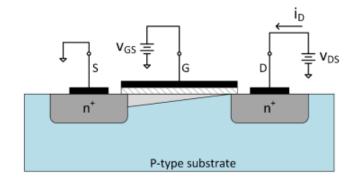


- $\square$  As  $v_{DS}$  increases:
  - Voltage varies along the channel
    - $\mathbf{v}_S$  near the source,  $v_D$  near the drain
  - Gate-to-channel voltage decreases closer to the drain
  - Channel depth decreases closer to the drain
    - Channel is tapered
- $\ \square$  More current flows with increasing  $v_{DS}$ , but channel resistance increases as channel becomes more tapered





#### **Channel Pinch-Off**



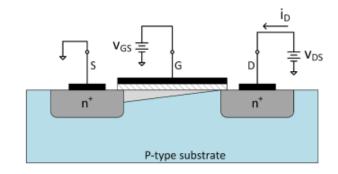
- $\Box$  Eventually, for large enough  $v_{DS}$ 
  - lacktriangle Gate-to-channel voltage near the drain no longer exceeds  $V_t$
  - Channel pinch-off occurs
  - Channel disappears at the edge of the drain
- □ Pinch-off occurs when:

$$v_{GD} = V_t = v_{GS} - v_{DS}$$
$$v_{DS} = v_{GS} - V_t$$



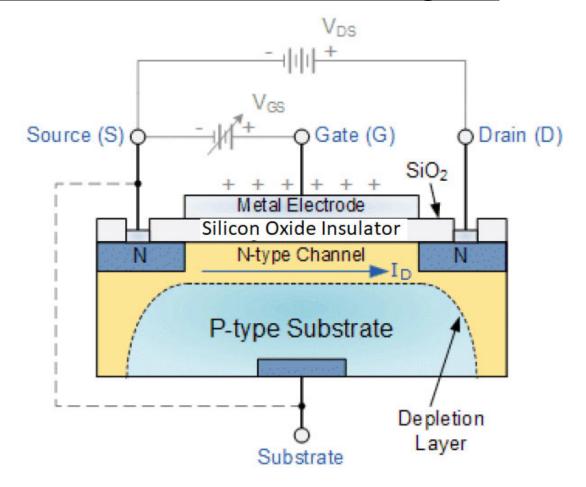
#### Saturation Region

- Once channel pinch-off occurs:
  - Voltage at the drain-end of the channel remains  $v_{OV}$ , even as  $v_{DS}$  increases
  - $v_{OV}$  is dropped across the depletion region surrounding the drain

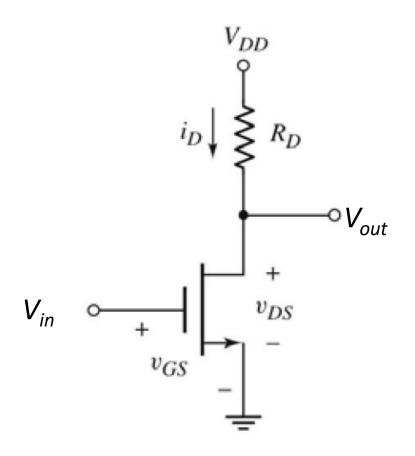


- $lue{}$  Voltage across the length of the channel is fixed at  $v_{ov}$
- lacktriangle Pinched-off channel shape does not change with  $v_{DS}$
- lacktriangle Drain current **saturates** at a constant value for constant  $v_{GS}$

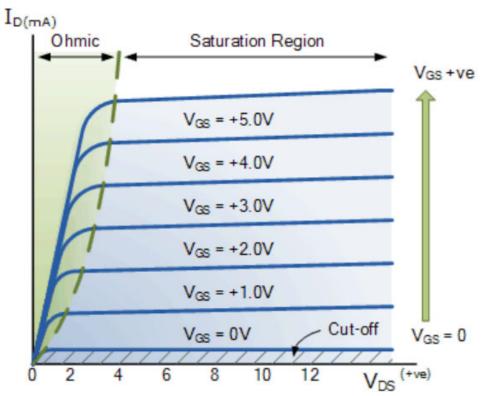


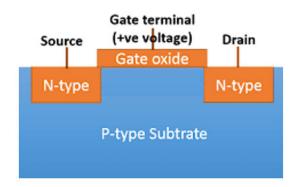










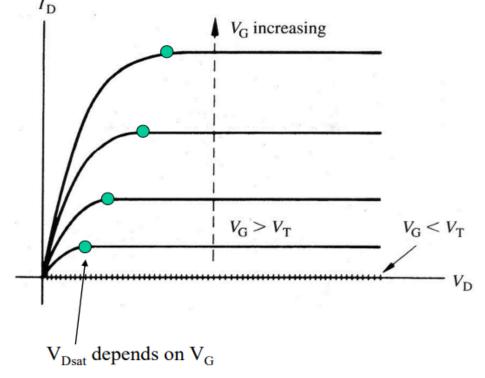


Relation between  $V_{DS}$  &  $V_{GS}$ 

Case	$V_T$	Channel condition	
Linear region	$V_{DS} < V_{GS} - V_T$	Continuous inversion from source to drain	
Pinch-off onset	$V_{DS}=V_{GS}-V_{T}$	Channel just disappears at drain end	
Saturation	$V_{DS} > V_{GS} - V_T$	Pinch-off near drain, depletion region forms, current saturates	

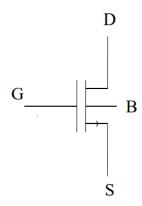


I<sub>D</sub>-V<sub>DS</sub> curves for various V<sub>GS</sub>:



n-channel MOS Transistor

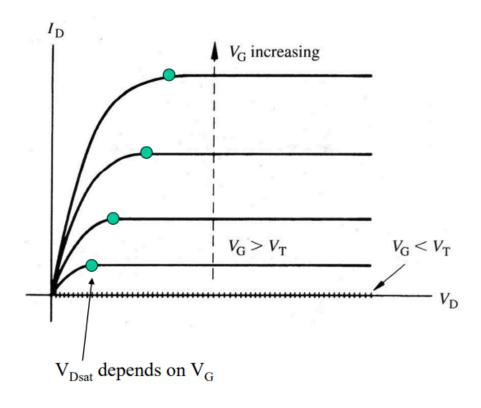
$$\beta = \mu C_{ox} \frac{W}{L}$$



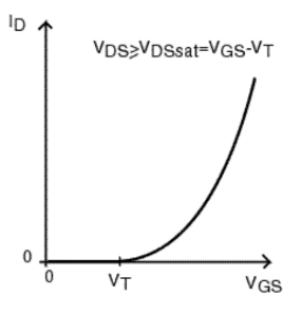
$$s = \begin{cases} 0 & V_{gs} < V_{t} & \text{cutoff} \\ \beta \left( V_{gs} - V_{t} - \frac{V_{ds}}{2} \right) V_{ds} & V_{ds} < V_{dsat} & \text{linear} \\ \frac{\beta}{2} \left( V_{gs} - V_{t} \right)^{2} & V_{ds} > V_{dsat} & \text{saturation} \end{cases}$$



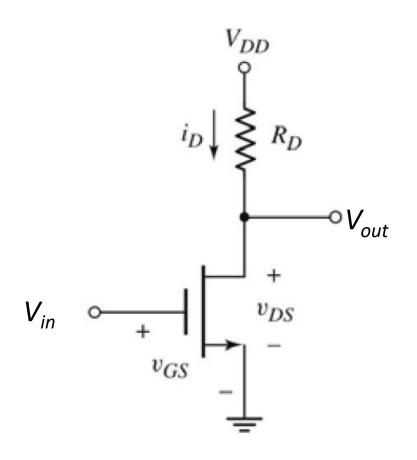
 $I_D$ - $V_{DS}$  curves for various  $V_{GS}$ :



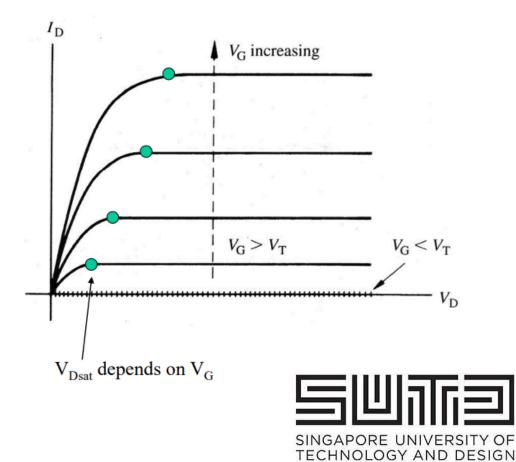
Transfer characteristics:

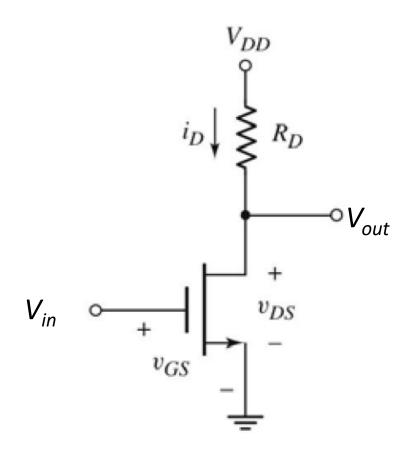




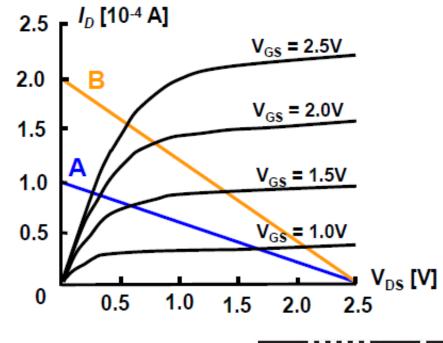


I<sub>D</sub>-V<sub>DS</sub> curves for various V<sub>GS</sub>:





#### **Load Line (Ckt Theory)**

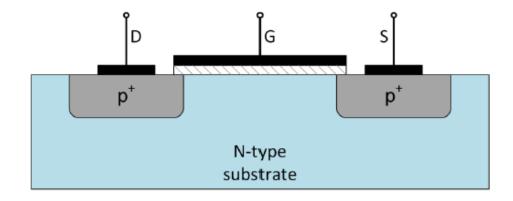




#### P-Channel MOSFETs

- Voltage polarities and doping types reversed relative to NMOS
  - N-type substrate
  - P+ drain and source

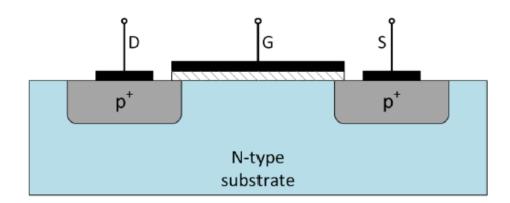
  - $lue{}$  Channel induced for  $v_{GS} \leq V_{tp}$
  - Substrate connected to source or most positive circuit voltage

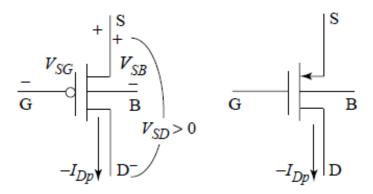




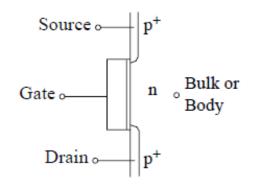
#### P-Channel MOSFETs

- Voltage polarities and doping types reversed relative to NMOS
  - N-type substrate
  - P+ drain and source
  - $lue{}$  Negative threshold voltage:  $V_{tp} < 0$
  - $lue{r}$  Negative overdrive voltage:  $v_{\it OV} = v_{\it GS} V_{\it tp} < 0$
  - lacktriangledown Channel induced for  $v_{\mathit{GS}} \leq V_{tp}$
  - Substrate connected to source or most positive circuit voltage



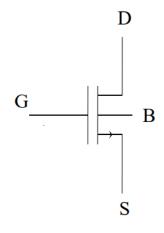


(b) p-channel MOSFET

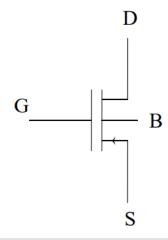




n-channel MOS Transistor



p-channel MOS Transistor

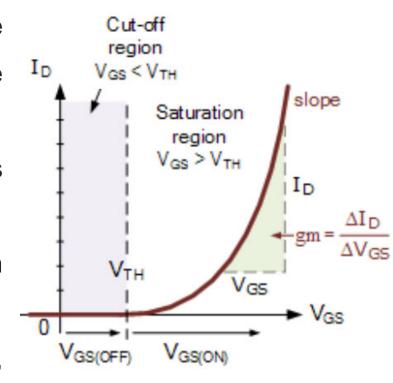


MOSFET type	V <sub>GS</sub> = +ve	V <sub>GS</sub> = 0	V <sub>GS</sub> = -ve
N-Channel	ON	OFF	OFF
P-Channel	OFF	OFF	ON



## MOSFET: Threshold Voltage (V<sub>th</sub>)

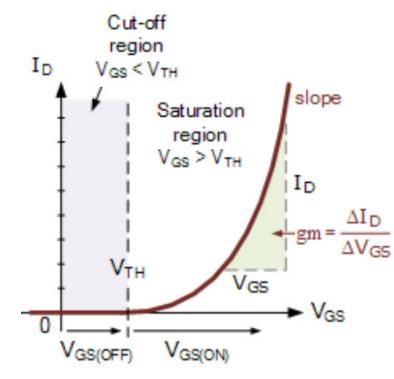
- The voltage needed on the Gate terminal of the MOSFET to form a thin channel beneath the gate electrode (between Source & Drain terminals).
- The current can flow between S and D terminals through the channel.
- So threshold voltage is the voltage needed to turn on the device.
- As the MOSFET is voltage controlled current source, the output current will depend on the gate voltage applied.



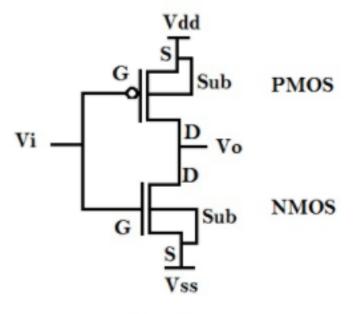


## MOSFET: Threshold Voltage (V<sub>th</sub>)

- Lower Vth:
  - Faster in timing
  - Higher subthreshold current
- Higher Vth:
  - Less leakage
  - Higher delay
- V<sub>th</sub> scales with MOSFET scaling







G = Gate Terminal

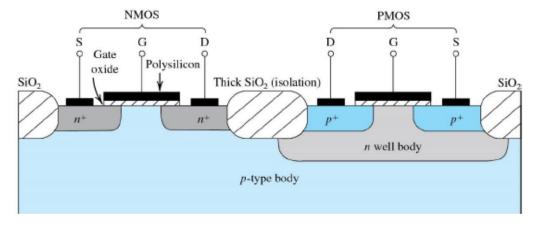
S = Source Terminal

D = Drain Terminal

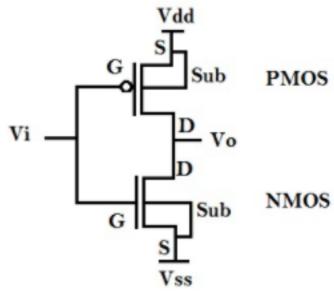
Sub = Substrate Terminal

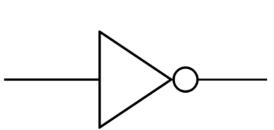
#### **CMOS**

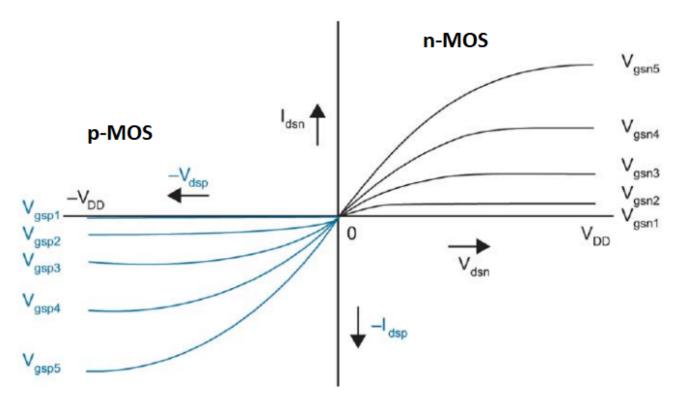
- Complementary MOS or CMOS
  - Both NMOS and PMOS fabricated on the same chip
- P-type substrate
- PMOS devices fabricated in n wells
- Most modern MOS chips are fabricated using CMOS technology



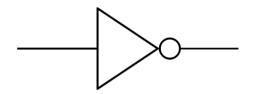


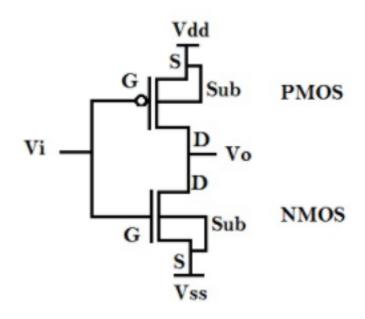




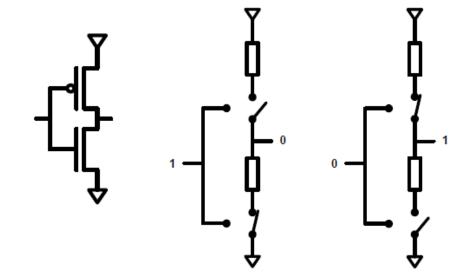






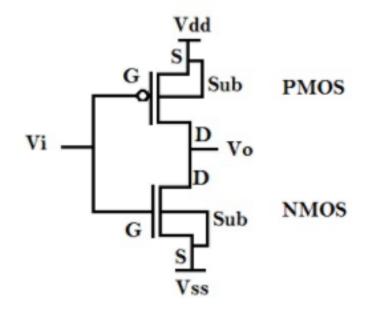


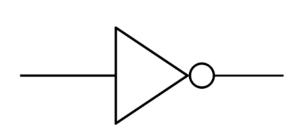
#### **CMOS Inverter Operation Principle**

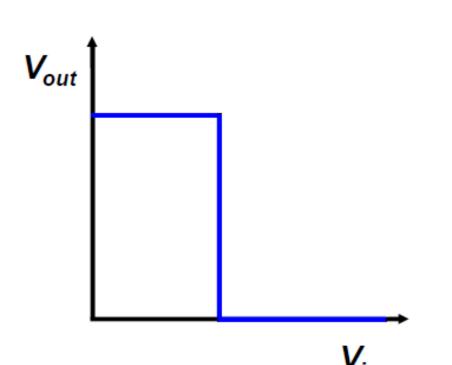




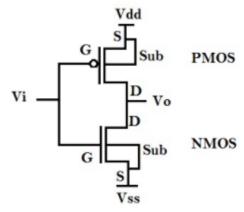
#### The Ideal Inverter

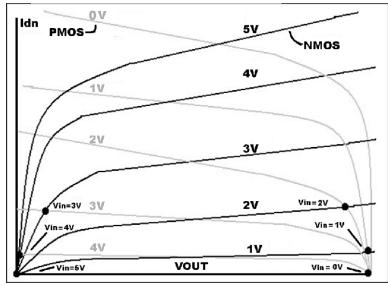




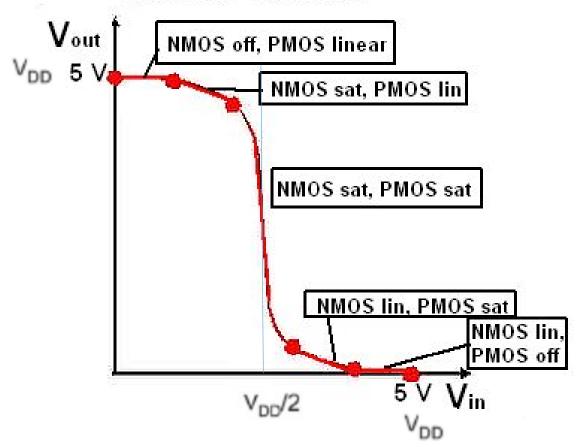






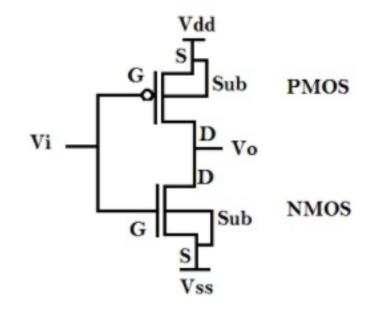


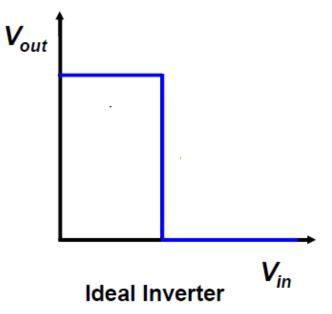
# CMOS inverter transfer function

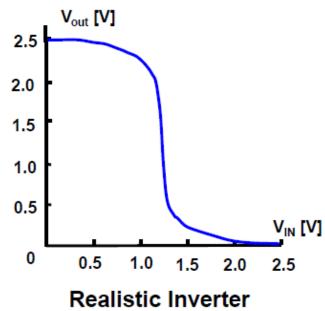


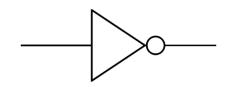


#### The Realistic Inverter

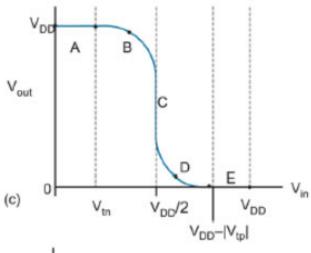


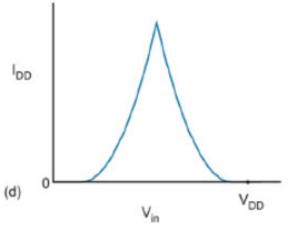


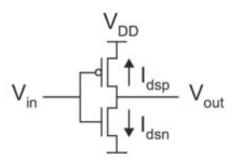










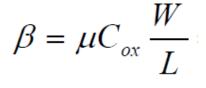


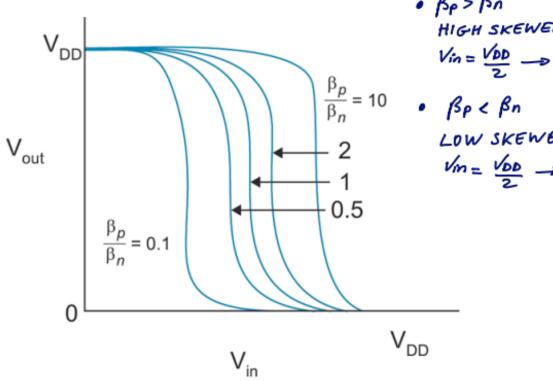
A CMOS inverter

Region	Condition	p-device	n-device	Output
A	$0 \le V_{\rm in} < V_{tn}$	linear	cutoff	$V_{\text{out}} = V_{DD}$
В	$V_{tn} \le V_{in} < V_{DD}/2$	linear	saturated	$V_{\rm out} > V_{DD}/2$
C	$V_{\rm in} = V_{DD}/2$	saturated	saturated	$V_{ m out}$ drops sharply
D	$V_{DD}/2 < V_{\rm in} \le V_{DD} -  V_{tp} $	saturated	linear	$V_{\rm out} < V_{DD}/2$
E	$V_{\rm in} > V_{DD} -  V_{tp} $	cutoff	linear	$V_{\text{out}} = 0$

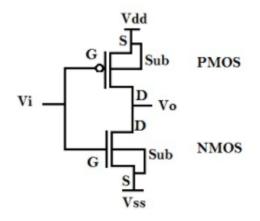


If  $\beta_p / \beta_n \neq 1$ , switching point will move from  $V_{DD}/2$ 





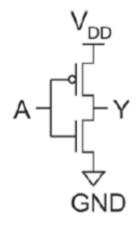
- · Bp > Bn HIGH SKEWED inverter  $V_{in} = \frac{V_{DD}}{2} \rightarrow V_{out} > \frac{V_{DD}}{2}$
- $\beta p < \beta n$ LOW SKEWED inverter  $\sqrt{m} = \frac{\sqrt{bb}}{2} \rightarrow \sqrt{out} < \frac{\sqrt{bb}}{2}$

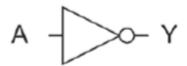




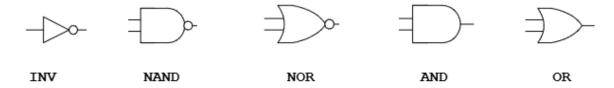
# CMOS Inverter (= NOT gate)

Table 1.1	Inverter truth table		
Α		Υ	
0		1	
1		0	



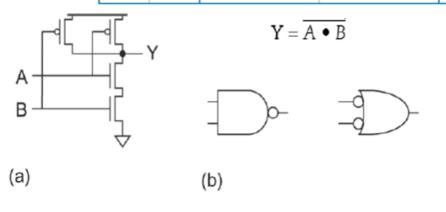




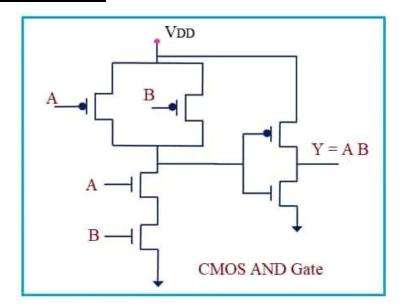


### **CMOS Logic NAND**

Table 1.2 NAND gate truth table				
Α	В	pull-down network	pull-up network	Υ
0	0	OFF	ON	1
0	1	OFF	ON	1
1	0	OFF	ON	1
1	1	ON	OFF	0

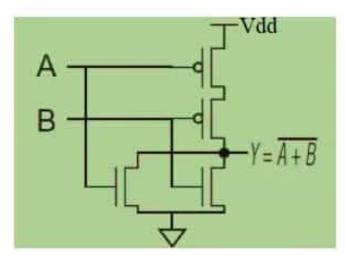


#### **AND Gate**



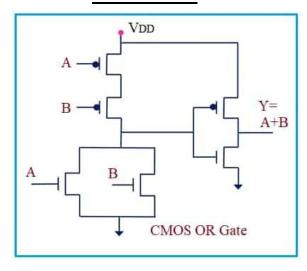


#### **NOR Gate**



А	В	A <b>NOR</b> B
0	0	1
0	1	0
1	0	0
1	1	0

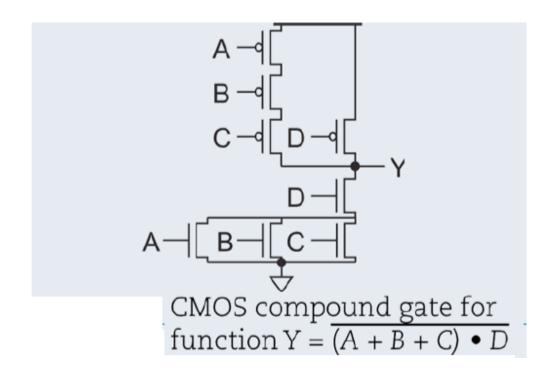
#### **OR Gate**



Α	В	Output (A OR B)
0	0	0
0	1	1
1	0	1
1	1	1



## **Compound gates**





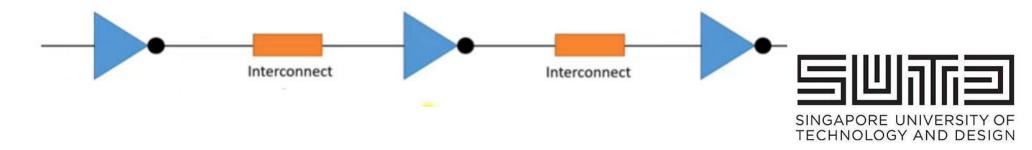
- Noise margin is the ratio by which the signal exceeds the minimum acceptable amount.
- It explains up to what extent IC allows noise in the transmission of logic '0' and logic '1'.
- Logic '0' and '1' represent the range of input values
- Hence, for error free digital signal transmission noise margin is required



- Noise margin refers to how much unwanted noise (disturbance in voltage levels) a circuit can tolerate without misinterpreting logic levels. It essentially defines the safety "buffer" between valid logic-0 and logic-1 signals.
- Noise margin is critical in digital IC design because it ensures reliable operation in the presence of crosstalk, supply fluctuations, or electromagnetic interference.
- Higher VDD gives bigger absolute noise margins, but modern technology scales VDD down, so circuit design must ensure sufficient margins.



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